1. MATERIALS:
   LEAD FRAME: COPPER 194P, THK = 0.203±0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5μm – 7.6μm) THICK.
   GOLD PLATE PER MIL-C-45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICROINCHES (1μm – 2μm) THICK).
   BODY SURFACE FINISH: VDI 21–24 (1.12–1.6 μm).

3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220.